# **Dual Complementary General Purpose Transistor**

The NST3946DP6T5G device is a spin-off of our popular SOT-23/SOT-323/SOT-563 three-leaded device. It is designed for general purpose amplifier applications and is housed in the SOT-963 six-leaded surface mount package. By putting two discrete devices in one package, this device is ideal for low-power surface mount applications where board space is at a premium.

### Features

- h<sub>FE</sub>, 100-300
- Low  $V_{CE(sat)}$ ,  $\leq 0.4 V$
- Simplifies Circuit Design
- Reduces Board Space
- Reduces Component Count
- This is a Pb-Free Device

### MAXIMUM RATINGS

Rating	Symbol	Value	Unit	
Collector – Emitter Voltage		V <sub>CEO</sub>	40	Vdc
Collector – Base Voltage		V <sub>CBO</sub>	60	Vdc
Emitter-Base Voltage		V <sub>EBO</sub>	6.0	Vdc
Collector Current – Continuous		Ι <sub>C</sub>	200	mAdc
Electrostatic Discharge	HBM MM	ESD Class	2 B	

### THERMAL CHARACTERISTICS

Characteristic (Single Heated)	Symbol	Max	Unit
Total Device Dissipation $T_A = 25^{\circ}C$ Derate above 25°C (Note 1)	P <sub>D</sub>	240 1.9	mW mW/°C
Thermal Resistance, Junction-to-Ambient (Note 1)	$R_{\thetaJA}$	520	°C/W
Total Device Dissipation $T_A = 25^{\circ}C$ Derate above 25°C (Note 2)	P <sub>D</sub>	280 2.2	mW mW/°C
Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{\theta JA}$	446	°C/W
Characteristic (Dual Heated) (Note 3)	Symbol	Max	Unit
Total Device Dissipation $T_A = 25^{\circ}C$ Derate above 25°C (Note 1)	P <sub>D</sub>	350 2.8	mW mW/°C
Thermal Resistance, Junction-to-Ambient (Note 1)	$R_{\theta JA}$	357	°C/W
Total Device Dissipation $T_A = 25^{\circ}C$ Derate above 25°C (Note 2)	P <sub>D</sub>	420 3.4	mW mW/°C
Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{\theta JA}$	297	°C/W
Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	–55 to +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

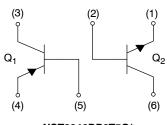
FR-4 @ 100 mm<sup>2</sup>, 1 oz. copper traces, still air.
FR-4 @ 500 mm<sup>2</sup>, 1 oz. copper traces, still air.

3. Dual heated values assume total power is sum of two equally powered channels



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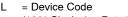
NST3946DP6T5G\*

\*Q1 PNP Q2 NPN



### **MARKING DIAGRAM**





- (180° Clockwise Rotation)
- = Date Code М

= Pb-Free Package

(Note: Microdot may be in either location)

#### **ORDERING INFORMATION**

De	Device Package Shi		Shipping <sup>†</sup>
NST3946	DP6T5G	SOT-963 (Pb-Free)	8000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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## **ELECTRICAL CHARACTERISTICS** (T<sub>A</sub> = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit	
OFF CHARACTERISTICS		•			
$      Collector - Emitter Breakdown Voltage (Note 4) \\ (I_C = 1.0 mAdc, I_B = 0) \\ (I_C = -1.0 mAdc, I_B = 0) $	(NPN) (PNP)	V <sub>(BR)CEO</sub>	40 -40		Vdc
Collector – Base Breakdown Voltage ( $I_C = 10 \ \mu Adc, I_E = 0$ ) ( $I_C = -10 \ \mu Adc, I_E = 0$ )	(NPN) (PNP)	V <sub>(BR)CBO</sub>	60 -40		Vdc
Emitter – Base Breakdown Voltage ( $I_E = 10 \ \mu Adc, I_C = 0$ ) ( $I_E = -10 \ \mu Adc, I_C = 0$ )	(NPN) (PNP)	V <sub>(BR)EBO</sub>	6.0 -5.0		Vdc
Collector Cutoff Current ( $V_{CE} = 30 \text{ Vdc}, V_{EB} = 3.0 \text{ Vdc}$ ) ( $V_{CE} = -30 \text{ Vdc}, V_{EB} = -3.0 \text{ Vdc}$ )	(NPN) (PNP)	ICEX		50 –50	nAdc
ON CHARACTERISTICS (Note 4)					
$      DC Current Gain \\ (I_C = 0.1 mAdc, V_{CE} = 1.0 Vdc) \\ (I_C = 1.0 mAdc, V_{CE} = 1.0 Vdc) \\ (I_C = 10 mAdc, V_{CE} = 1.0 Vdc) \\ (I_C = 50 mAdc, V_{CE} = 1.0 Vdc) \\ (I_C = 100 mAdc, V_{CE} = 1.0 Vdc) $	(NPN)	h <sub>FE</sub>	40 70 100 60 30	- - 300 - -	_
	(PNP)		60 80 100 60 30	_  300 _ _	
Collector – Emitter Saturation Voltage ( $I_C = 10 \text{ mAdc}, I_B = 1.0 \text{ mAdc}$ ) ( $I_C = 50 \text{ mAdc}, I_B = 5.0 \text{ mAdc}$ )	(NPN)	V <sub>CE(sat)</sub>		0.2 0.3	Vdc
$(I_{\rm C}$ = -10 mAdc, $I_{\rm B}$ = -1.0 mAdc) $(I_{\rm C}$ = -50 mAdc, $I_{\rm B}$ = -5.0 mAdc)	(PNP)			-0.25 -0.4	
Base – Emitter Saturation Voltage ( $I_C = 10 \text{ mAdc}, I_B = 1.0 \text{ mAdc}$ ) ( $I_C = 50 \text{ mAdc}, I_B = 5.0 \text{ mAdc}$ )	(NPN)	V <sub>BE(sat)</sub>	0.65	0.85 0.95	Vdc
( $I_C = -10$ mAdc, $I_B = -1.0$ mAdc) ( $I_C = -50$ mAdc, $I_B = -5.0$ mAdc)	(PNP)		-0.65 -	-0.85 -0.95	

4. Pulse Test: Pulse Width  $\leq$  300 µs; Duty Cycle  $\leq$  2.0%.

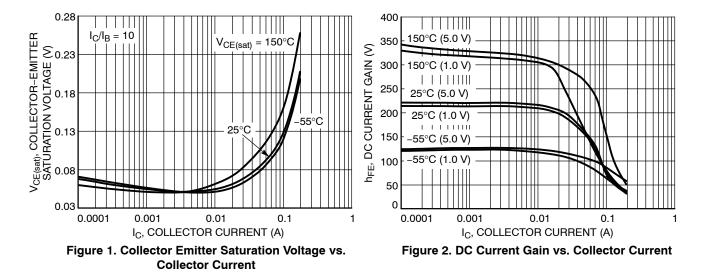
## **ELECTRICAL CHARACTERISTICS** (T<sub>A</sub> = $25^{\circ}$ C unless otherwise noted) (Continued)

Characteristic	Symbol	Min	Мах	Unit	
SMALL-SIGNAL CHARACTERISTICS					
$\label{eq:current-Gain-Bandwidth Product} \begin{aligned} &(I_C = 10 \text{ mAdc}, V_{CE} = 20 \text{ Vdc}, \text{ f} = 100 \text{ MHz}) \\ &(I_C = -10 \text{ mAdc}, V_{CE} = -20 \text{ Vdc}, \text{ f} = 100 \text{ MHz}) \end{aligned}$	(NPN) (PNP)	f <sub>T</sub>	200 250		MHz
Output Capacitance (V <sub>CB</sub> = 5.0 Vdc, I <sub>E</sub> = 0, f = 1.0 MHz) (V <sub>CB</sub> = -5.0 Vdc, I <sub>E</sub> = 0, f = 1.0 MHz)	(NPN) (PNP)	C <sub>obo</sub>		4.0 4.5	pF
Input Capacitance (V <sub>EB</sub> = 0.5 Vdc, $I_C$ = 0, f = 1.0 MHz) (V <sub>EB</sub> = -0.5 Vdc, $I_C$ = 0, f = 1.0 MHz)	(NPN) (PNP)	C <sub>ibo</sub>		8.0 10.0	pF
Noise Figure (V <sub>CE</sub> = 5.0 Vdc, I <sub>C</sub> = 100 $\mu$ Adc, R <sub>S</sub> = 1.0 k $\Omega$ , f = 1.0 kHz) (V <sub>CE</sub> = -5.0 Vdc, I <sub>C</sub> = -100 $\mu$ Adc, R <sub>S</sub> = 1.0 k $\Omega$ , f = 1.0 kHz)	(NPN) (PNP)	NF		5.0 4.0	dB

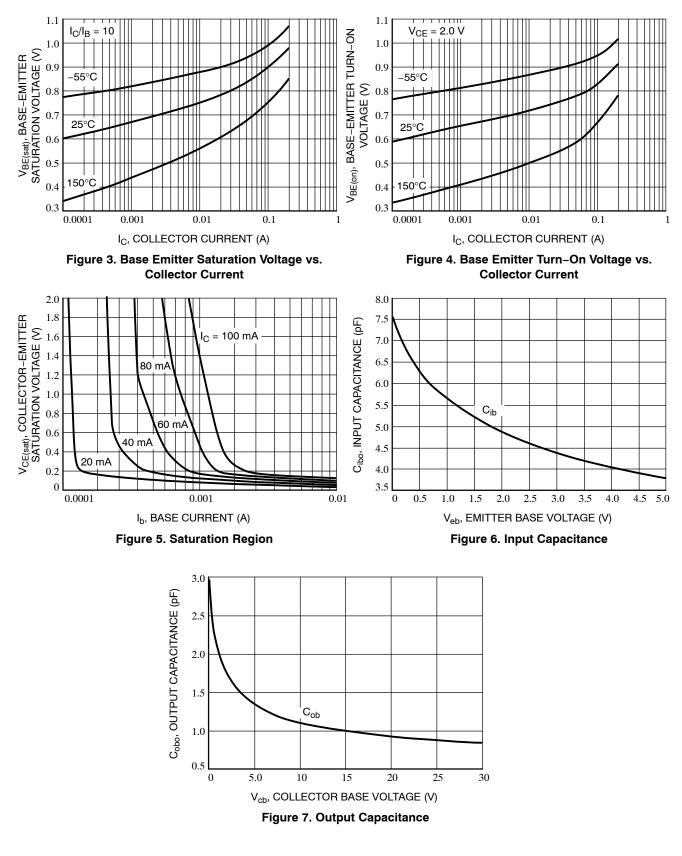
#### SWITCHING CHARACTERISTICS

Delay Time		(NPN) (PNP)	t <sub>d</sub>	-	35 35	
Rise Time	$(I_{C} = 10 \text{ mAdc}, I_{B1} = 1.0 \text{ mAdc})$ $(I_{C} = -10 \text{ mAdc}, I_{B1} = -1.0 \text{ mAdc})$	(NPN) (PNP)	t <sub>r</sub>	-	35 35	ns
Storage Time	$(V_{CC} = 3.0 \text{ Vdc}, I_C = 10 \text{ mAdc})$ $(V_{CC} = -3.0 \text{ Vdc}, I_C = -10 \text{ mAdc})$	(NPN) (PNP)	t <sub>s</sub>	-	275 250	20
Fall Time	$(I_{B1} = I_{B2} = 1.0 \text{ mAdc})$ $(I_{B1} = I_{B2} = -1.0 \text{ mAdc})$	(NPN) (PNP)	t <sub>f</sub>		50 50	ns

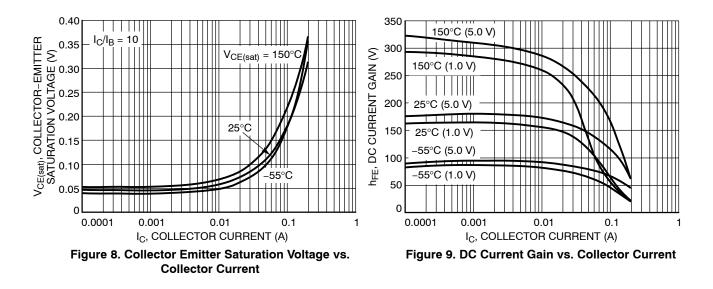
### NPN TRANSISTOR



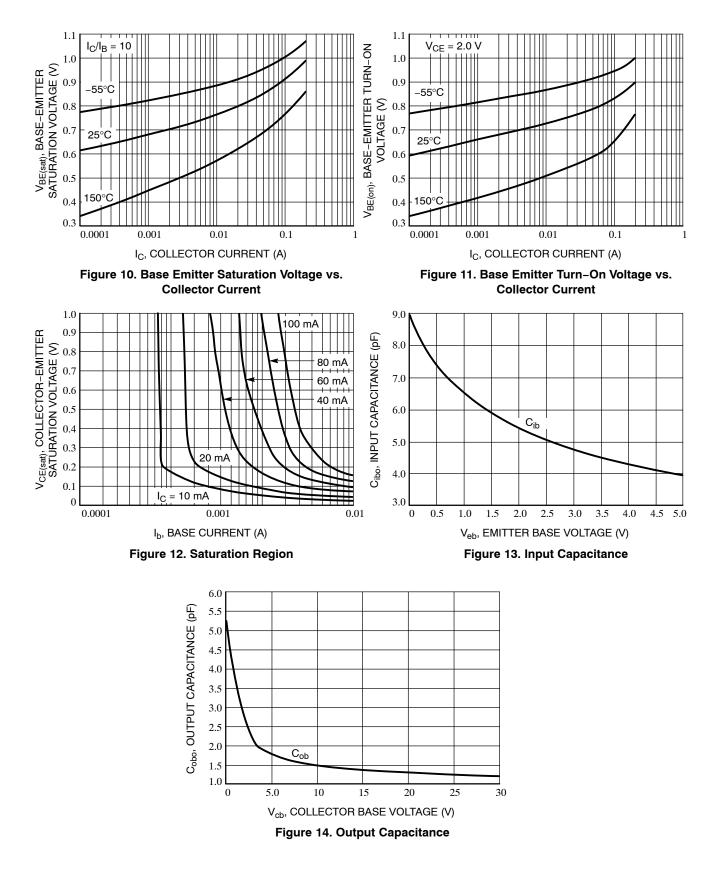
#### NPN TRANSISTOR



### **PNP TRANSISTOR**

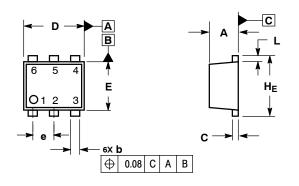


### **PNP TRANSISTOR**



#### PACKAGE DIMENSIONS

SOT-963 CASE 527AD-01 ISSUE C



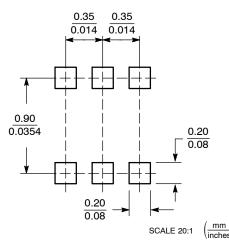
NOTES 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: MILLIMETERS

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MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

	MILLIMETERS		INCHES			
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.34	0.37	0.40			
b	0.10	0.15	0.20	0.004	0.006	0.008
С	0.07	0.12	0.17	0.003	0.005	0.007
D	0.95	1.00	1.05	0.037	0.039	0.041
E	0.75	0.80	0.85	0.03	0.032	0.034
е	0.35 BSC			(	0.014 BS	C
L	0.05	0.10	0.15	0.002	0.004	0.006
ΗE	0.95	1.00	1.05	0.037	0.039	0.041

SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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